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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/744,227	01/22/2001	Hidetaka Higashino	NAK1-BN65	3963
21611	7590	05/20/2004	EXAMINER	
SNELL & WILMER LLP			DONG, DALEI	
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SUITE 1200				
IRVINE, CA 92614-7230			ART UNIT	PAPER NUMBER
			2879	

DATE MAILED: 05/20/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	09/744,227	HIGASHINO ET AL.
Examiner	Art Unit	
Dalei Dong	2879	

-- The MAILING DATE of this communication app appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 12 March 2004.

2a) This action is **FINAL**. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) See Continuation Sheet is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) Claim(s) _____ is/are allowed.

6) Claim(s) 1,3,5,7,9,11,13,15,17,19,21,23,25,27,29,31,33,35,37,39,41-47,50 and 51 is/are rejected.

7) Claim(s) _____ is/are objected to.

8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 05 September 2003 is/are: a) accepted or b) objected to by the Examiner.

 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) All b) Some * c) None of:
1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____

4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____

5) Notice of Informal Patent Application (PTO-152)
6) Other: _____

DETAILED ACTION

Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.
2. Claims 1, 5, 9, 13, 41-47 and 50 rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent No. 5,938,494 to Betsui in view of U.S. Patent No. 6,236,159 to Inoue.

Regarding to claims 1, 5, 9, 13, 41-47 and 50, Betsui discloses in Figures 3-4C, a "pair of substrates may be composed of a front substrate and a rear substrate. These substrates may be made of glass" (column 3, line 3-5).

Betsui also discloses in Figures 3-4C, "as the sealing medium used for sealing the periphery of the substrates for assembling the panel, usable are low-melting glass and various kinds of organic materials" (column 3, line 28-30).

Betsui further discloses in Figures 3-4C, "the removal of the temporary protective film may be carried out by introducing a gas for electric discharge for removal into the discharge space between the pair of substrates, and then applying voltage to generate electric discharge between the electrodes to etch the temporary protective film" (column 3, line 31-37).

Betsui further yet discloses in Figures 3-4C, "after the removal of the temporary protective film, the discharge gas for removal is taken out from the inside of the panel

and then the discharge gas for display is introduced into the panel. This discharge gas for display is to be used when the panel is used as a finished product. Alternatively, a getter may be provided in the panel, and the discharge gases for display and for removal of the temporary protective film by electric charge, the getter is activated to remove the discharge gas for removal contained from the inside of the panel" (column 3, line 41-51).

However, Betsui does not disclose a partition walls and the substeps for the exhaust step specified in the limitations. Inoue teaches, "after fabrication of the panel, an evacuation and gas introduction process is performed in the following manner. The panel is evacuated *a substep of evacuating the envelope* from at least one or the vent holes. The impurity gases are caused to be released from the barrier ribs, the sealing member and the like in the panel and expelled from the inter-rib spaces by some means. The release of the impurity gases may be achieved, for example, by heating the panel or by causing electric discharge between discharge electrodes or between the cleaning electrodes while introducing the gas into the panel. These methods may be employed in the combination" (column 6, line 66-67 to column 7, line 1-9).

Inoue also teaches "the impurity gases remaining in the inter-rib spaces within the panel are forcibly expelled from the second vent hole by introducing the discharge gas or the cleaning gas *a substep for filling the envelope with a cleaning gas that includes as a constituent a gas that is substantially causes no impurity in the discharge gas*, e.g., N₂, Ne, He, Ar or gas mixture thereof, into the panel from the first vent hole. Alternatively, the impurity gases may be removed from the inter-rib spaces by guiding the impurity gases to the getter to allow the getter to absorb the impurity gases. Thereafter, the

introduction of the gas is stopped, while the panel is continuously evacuated *a substep for re-evacuating the envelope*. This operation may be repeated several times as required" (column 7, line 10-19).

Inoue further teaches, "the panel is cooled to room temperature, and the evacuation is stopped. Then, the discharge gas is introduced into the panel until the internal pressure of the panel reaches a desired level, and the vent pipes attached to the panel is sealed" (column 7, line 20-24).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to have utilize the gas flow barrier along with the evacuation and gas introduction process of Inoue for the manufacturing process of a gas discharge panel of Betsui in order to ensure complete removal of impurity gases in inter-rib spaces of the panel by providing a gas flow barrier in a peripheral space of the panel to allow the inter-rib spaces to have a greater gas flow conductance than the peripheral space.

3. Claims 3, 7, 11, 15, 17, 19, 21, 23, 25, 27, 29, 31, 33, 35, 37, 39 and 51, are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent No. 5,938,494 to Betsui in view of U.S. Patent No. 6,236,159 to Inoue in further view of U.S. Patent No. 6,332,821 to Park.

Regarding to claims 3, 7, 11, 15, 17, 19, 33, 35, 37 and 39, Betsui discloses a method of producing a gas discharge panel comprising an envelope forming step for forming an envelope by providing over a first plate a second plate so the second plate faces a main surface of the first plate, a sealing step for sealing the envelope with a

sealant along outer edges of the first and second plates, an exhaust step for exhausting gas from the envelope and a filling step for filling the envelope with a discharge gas.

However, Betsui does not disclose partition walls for partitioning light emitting cells and the exhaust substeps specified in the limitation and a pressure in the envelope is set lower than a pressure outside the envelope. Inoue teaches a partition walls and the exhaust steps including a substep for evacuating the envelope; a substep for filling the envelope with a cleaning gas and a substep for re-evacuating the envelope.

However, Inoue fails to teach a pressure in the envelope is set lower than a pressure outside the envelope. Park teaches "the exhaustion of air within both the assembly 20 itself and the heating chamber 31 is carried out via the piping 33 and 33' simultaneously. At this time, the first, second and fourth valves 34, 35 and 37 are opened and the third valve 36 is closed. When the air begins to evacuated, the heating chamber 31 begins to be heated by the heater 30 simultaneously. The temperature of the heating chamber 31 is raised to 400° C.-450° C. by heating" (column 5, line 4-10).

Park also teaches, "when such evacuation and heating is carried out simultaneously, the frit glass 23 begins to melt at a temperature above 400°C. In addition, gases are generated from the frit glass 23, and such gases are exhausted out of the heating chamber 31 by the evacuation operation. The frit glass 23 melts between the substrate 11 and 12, and accordingly the substrate 11 and 12 are bonded by the pressure of the clips. At this time, the thickness of the frit glass 23 become thinner than the initial thickness, and consequently the partition walls 17 can closely contact the inner surface of the facing substrate 11" (column 5, line 11-21).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to have utilize the gas flow barrier along with the evacuation and gas introduction process of Inoue and the exhaustion of air within assembly of Park for the manufacturing process of a gas discharge panel of Betsui in order to ensure complete removal of impurity gases in inter-rib spaces of the panel by providing a gas flow barrier in a peripheral space of the panel to allow the inter-rib spaces to have a greater gas flow conductance than the peripheral space and thus provide an improved method for fabricating a plasma display device.

Regarding to claims 21, 23, 25, 27, 29, 31 and 51, Betsui discloses a method of producing a gas discharge panel comprising an envelope forming step for forming an envelope by providing over a first plate a second plate so the second plate faces a main surface of the first plate, a sealing step for sealing the envelope with a sealant along outer edges of the first and second plates, an exhaust step for exhausting gas from the envelope and a filling step for filling the envelope with a discharge gas.

However, Betsui does not disclose partition walls for partitioning light emitting cells and the exhaust substeps specified in the limitation and a pressure in the envelope is set lower than a pressure outside the envelope while a dry gas is circulated through the envelope. Inoue teaches a partition walls and the exhaust steps including a substep for evacuating the envelope; a substep for filling the envelope with a cleaning gas and a substep for re-evacuating the envelope.

However, Inoue fails to teach a pressure in the envelope is set lower than a pressure outside the envelope while a dry gas is circulated through envelope. Park teaches "the exhaustion of air within both the assembly 20 in itself and the heating chamber 31 is carried out via the piping 33 and the piping 33' simultaneously. At this time, the heating chamber 31 begins to be heated by the heater 30 simultaneously with the evacuation. The temperature of the heating chamber 31 is raised to 400.degree. C. - 450.degree. C. by heating. The frit glass 23 is melted by heating, and accordingly the substrates 11 and 12 are bonded. Gases are generated from the frit glass 23, and such gases are exhausted out of the heating chamber 31 by the evacuation operation" (column 6, line 19-28).

Park also teaches "then, when the device and chamber are cooled down to the first predetermined temperature, the evacuation of the heating chamber 31 and the assembly 20 is stopped, and the discharge gas is supplied to the assembly 20. It is preferable that the discharge gas be an inert rare gas, Ar or Ne, and the gas filling pressure is in the range of from 10 to 760 Torr" (column 6, line 29-34).

Park further teaches, "when the pressure of the discharge gas in the assembly reaches a predetermined pressure, the assembly 20 is evacuated again. It is preferable that such evacuation and filling of the discharge gas is repeated more than twice. It is effective for exhausting air and moisture remaining within the assembly 20 that the discharge gas is repeatedly filled and evacuated in a high temperature state" (column 6, 35-41).

Park further yet teaches, "after the above steps are finished, the assembly 20 and the heating chamber 31 are further cooled. The cooling is continued until the temperature of the assembly 20 reaches the second predetermined temperature in the range of 10.degree. C. to 100.degree. C., and it is preferable that the assembly 20 be cooled to room temperature. When the assembly 20 is cooled to the second predetermined temperature, another charge of the discharge gas is supplied to the assembly 20 to 100-700 Torr. After the discharge gas is supplied as above, the vent hole 21 is sealed to complete the display device assembly" (column 6, line 42-52).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to have utilize the gas flow barrier along with the evacuation and gas introduction process of Inoue and the exhaustion of air within assembly of Park for the manufacturing process of a gas discharge panel of Betsui in order to ensure complete removal of impurity gases in inter-rib spaces of the panel by providing a gas flow barrier in a peripheral space of the panel to allow the inter-rib spaces to have a greater gas flow conductance than the peripheral space and thus provide an improved method for fabricating a plasma display device.

Response to Arguments

4. Applicant's arguments filed September 5, 2003 have been fully considered but they are not persuasive.

In response to Applicant's primary argument that the Inoue does not teach an envelope filled with a cleaning gas after being evacuated and then re-evacuated in the

exhaust step; Examiner asserts that Inoue reference clearly and distinctively teaches the filling of a cleaning gas within an envelope after being evacuated and then re-evacuated set forth in column 6, line 66-67 to column 7, line 1-19. Thus, Examiner asserts that the Inoue reference is valid and maintains the rejection.

Also, in response to Applicant's argument that the method set forth in claim 1 can be accomplished with only one hole for both introducing and exhausting the gases. Examiner asserts that nowhere does the Applicant claim that the method requires only one hole for both introducing and exhausting the gases. Further, it is old and well known in the art to utilize only one hole for introducing and exhausting the gases as shown by the Park reference. Furthermore, Applicant as shown in Figure 3, utilizes two holes instead of one hole to introduce and exhaust gases. Thus, Examiner asserts that the prior art of record is valid and maintains the rejection.

Further, in response to Applicant's argument that Park reference fails to teach or suggest a differential pressure between the heating chamber that surrounds the envelope and the internal pressure within the envelope. Examiner agrees with the Applicant's assertion that the exhaustion of the air is within the heating chamber as well as the assembly or the envelope. However, Applicant fails to consider the prior art as a whole in that Park reference further teaches "when the device and the chamber are cooled down to the first predetermined temperature, the evacuation of the heating chamber 31 and the assembly 20 is stopped, and the discharge gas is supplied to the assembly 20" (column 6, line 29-32). Park reference then further goes on to teach "when the pressure of the discharge gas in the assembly reaches a predetermined pressure, the assembly 20 is

evacuated gain" (column 6, lines 35-37). Park reference furthermore teaches "it is effective for exhausting air and moisture remaining within the assembly 20" (column 6, lines 38-40) thus the Park reference creating a pressure difference between the heating chamber that surrounds the envelope and the internal pressure within the assembly or envelope by evacuating the assembly or the envelope and also by removing the residual air and moisture remained within the envelope. Thus, Examiner asserts that the Park reference is valid and maintains the rejection.

Conclusion

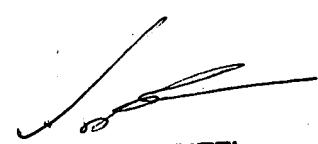
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dalei Dong whose telephone number is (571)272-2370. The examiner can normally be reached on 8 A.M. to 5 P.M..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nimeshkumar Patel can be reached on (571)272-2457. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

D.D.

May 12, 2004



VIP PATEL
PRIMARY EXAMINER